

FIG. 1A

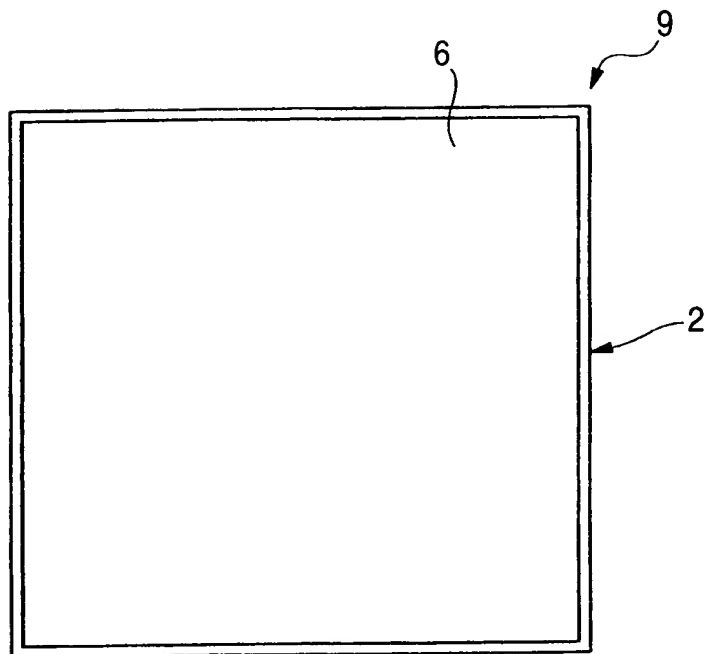
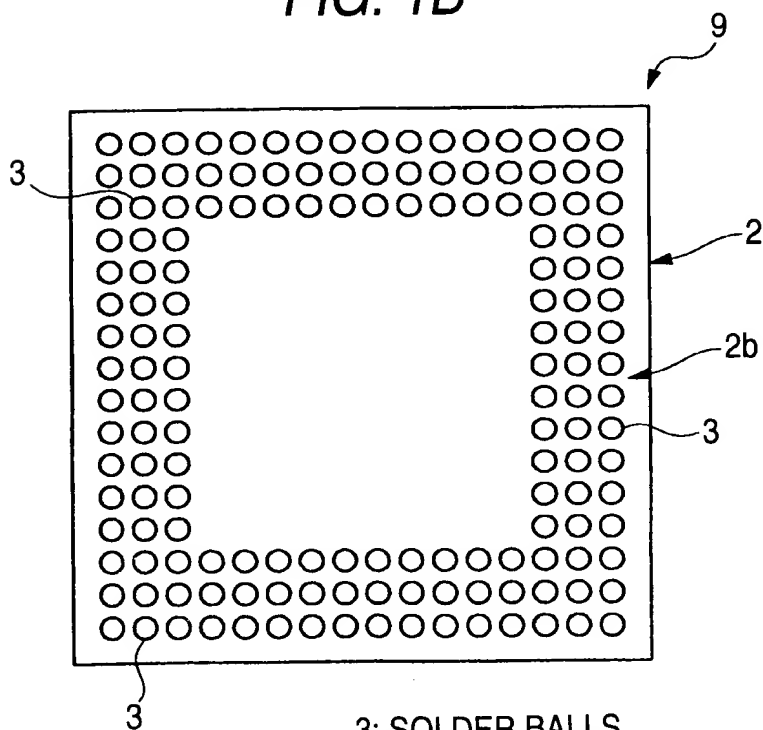
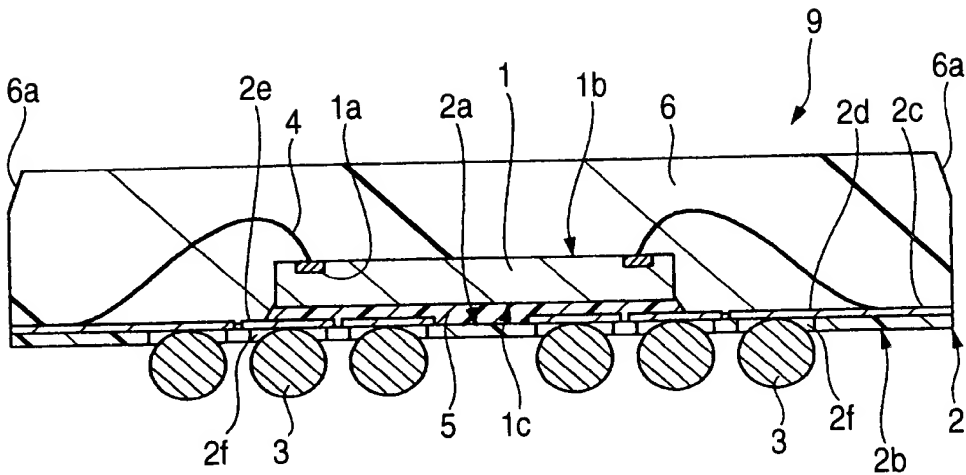


FIG. 1B



3: SOLDER BALLS  
6: SEALED PORTION  
9: CSP (SEMICONDUCTOR DEVICE)

**FIG. 2**



1a: PADS (SURFACE ELECTRODES)  
2c: CONNECTION TERMINALS (ELECTRODES)

FIG. 3A

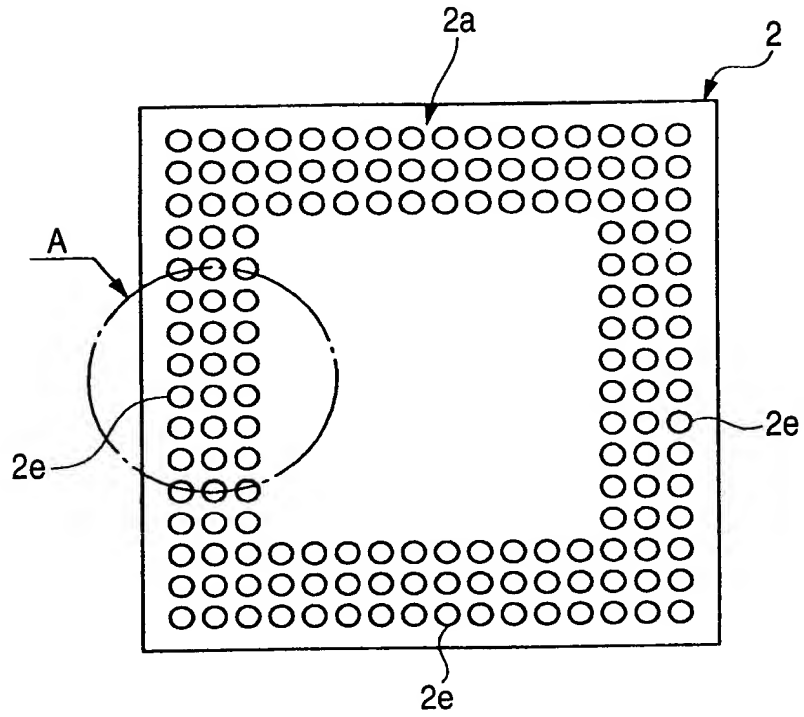


FIG. 3B

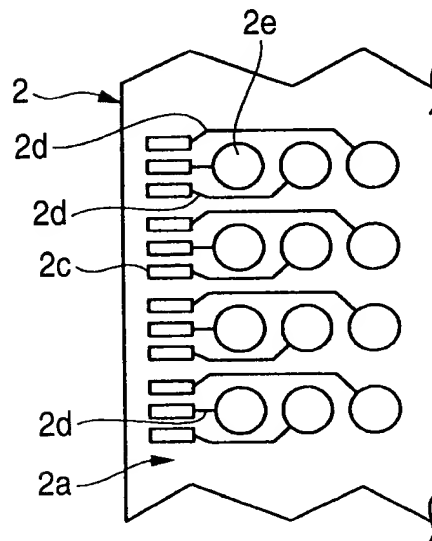
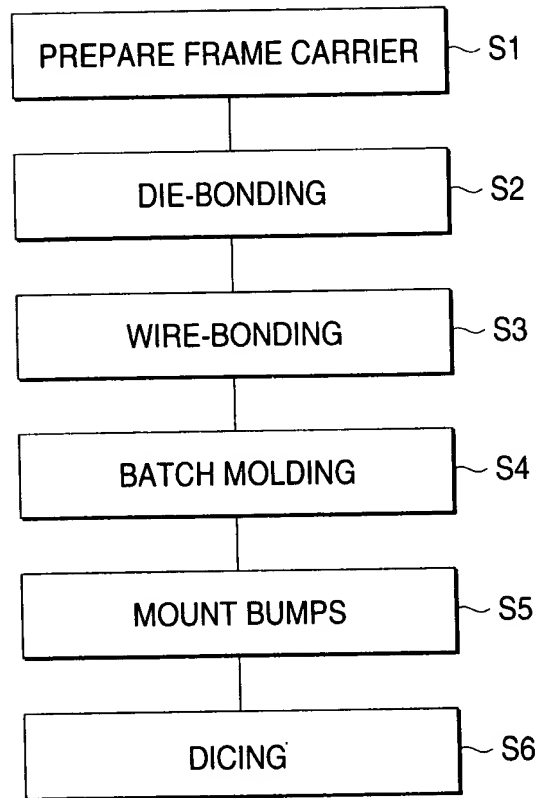


FIG. 4



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T06280"TS94E660

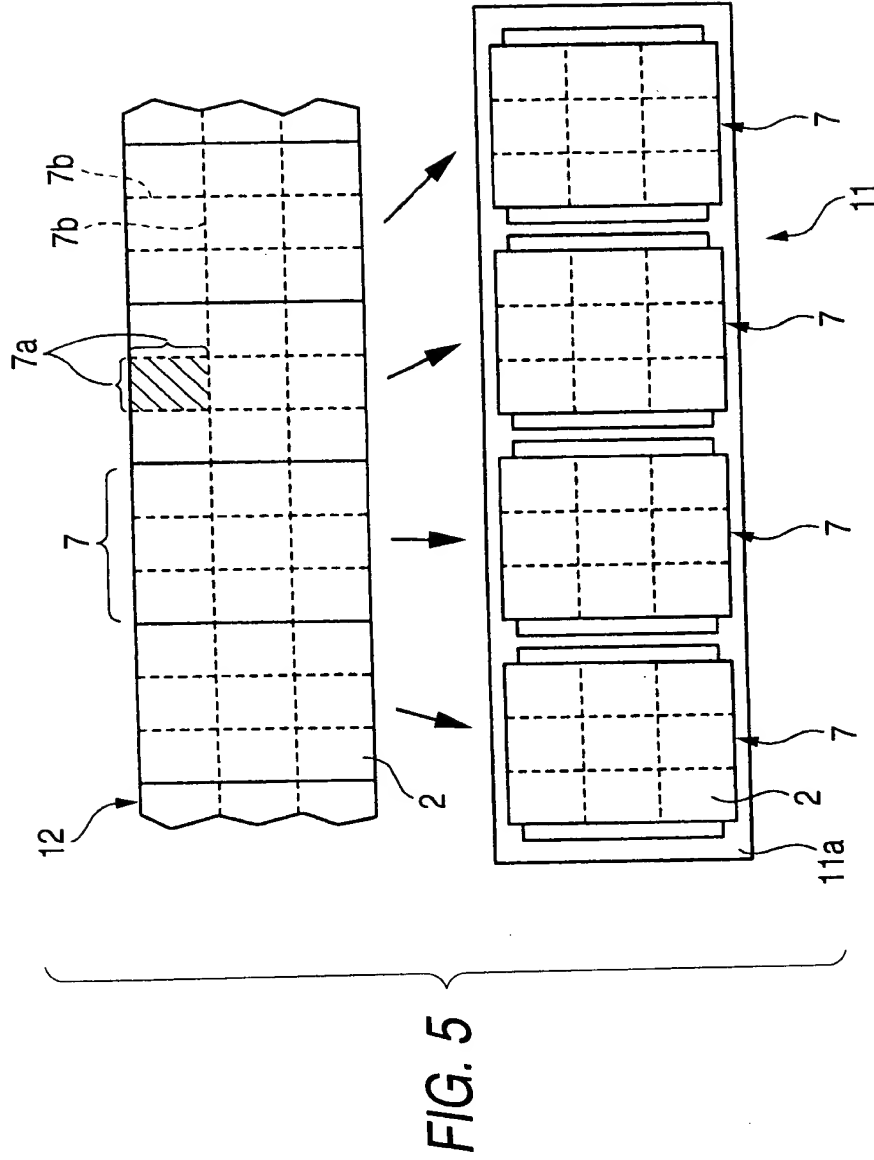


FIG. 6

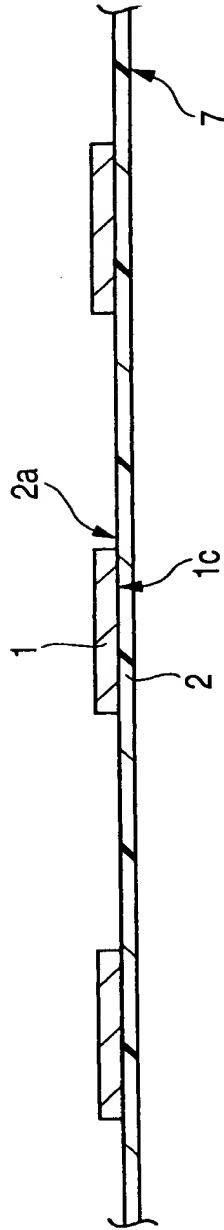
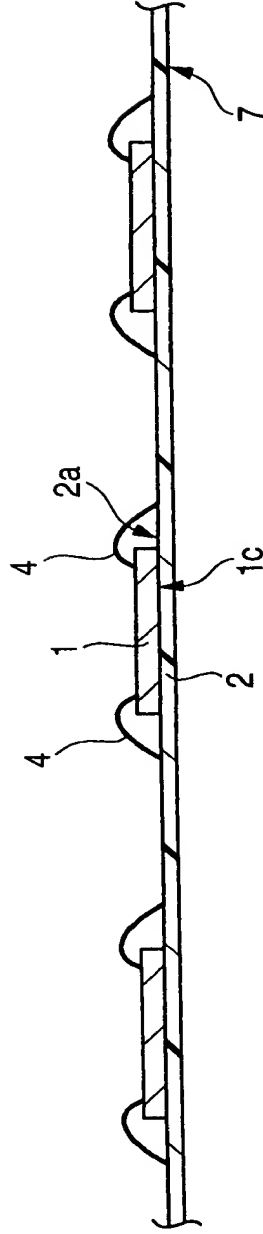


FIG. 7



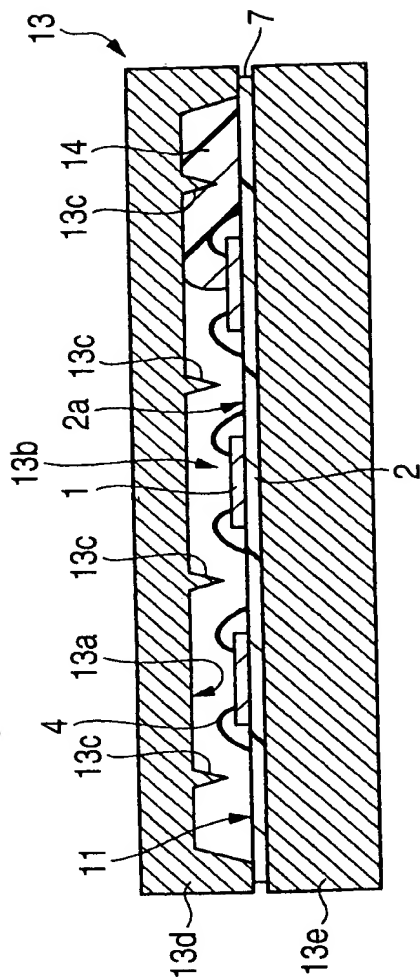
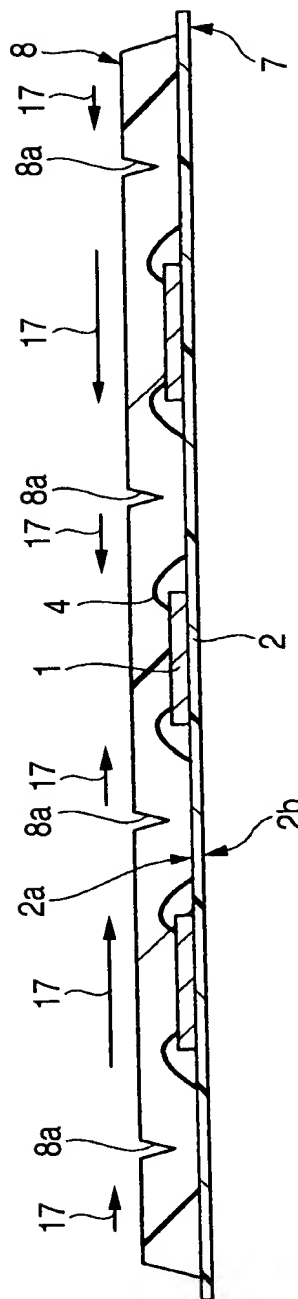


FIG. 8A

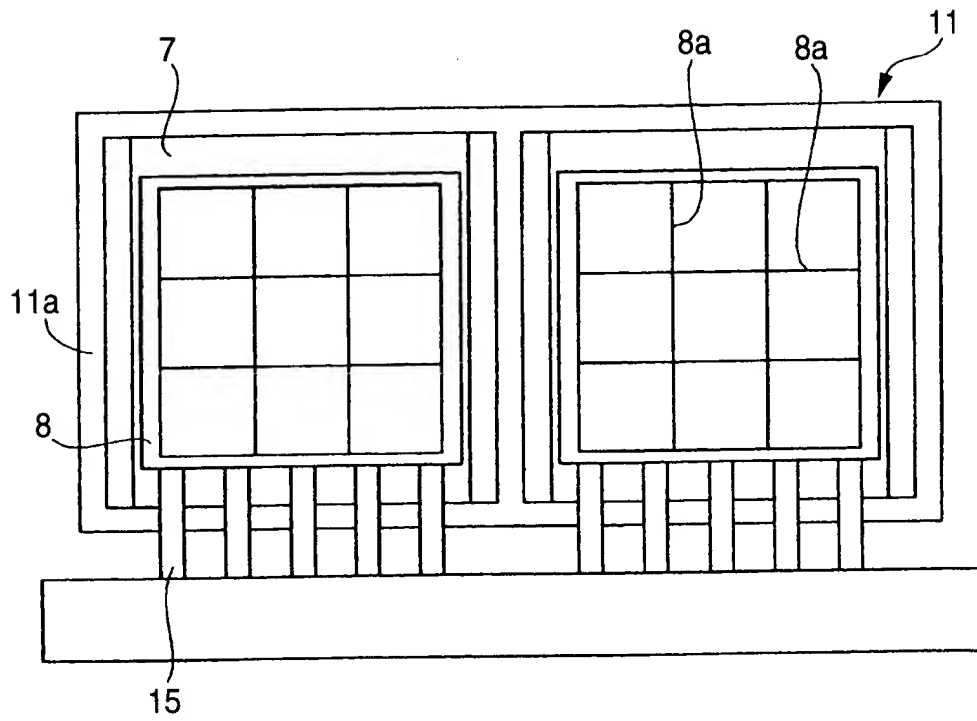
FIG. 8B



- 1: SEMICONDUCTOR CHIP
- 2: TAPE SUBSTRATE  
(CHIP SUPPORTING SUBSTRATE)
- 2a: CHIP SUPPORTING FACE
- 2b: BACK FACE (OPPOSITE FACE)
- 4: WIRES (CONDUCTIVE MEMBERS)
- 7: MULTI-DEVICE SUBSTRATE
- 8: BLOCK-MOLDED PORTION  
(BATCH-SEALED PORTION)
- 8a: GROOVES
- 13: MOLDING TOOL
- 13a: CAVITY FORMING FACE
- 13b: CAVITY
- 13c: PROTRUSIONS
- 14: MOLDING RESIN



FIG. 9



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FIG. 10

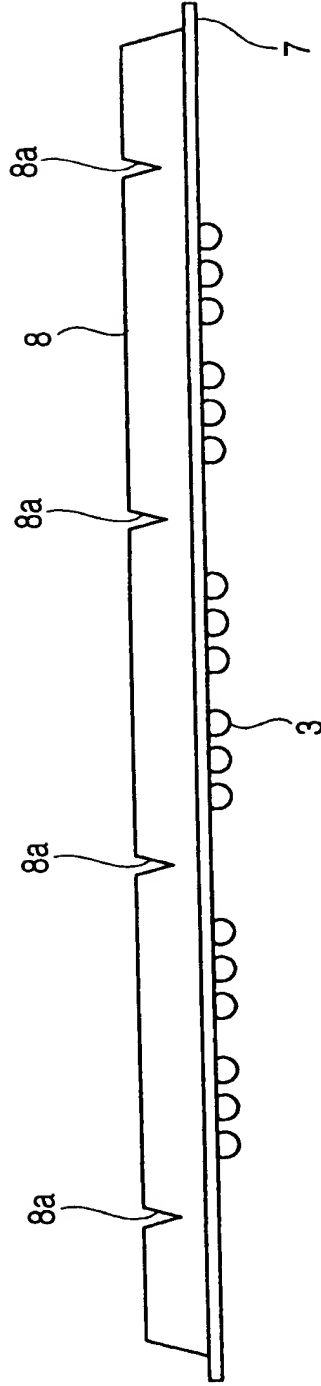
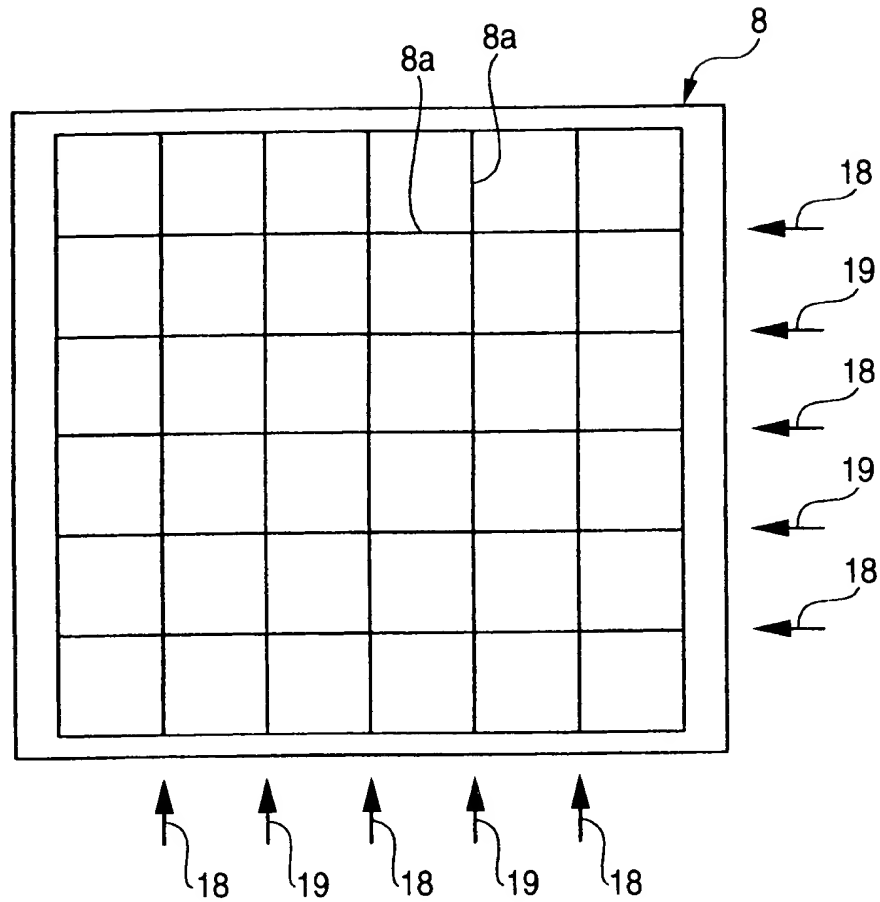


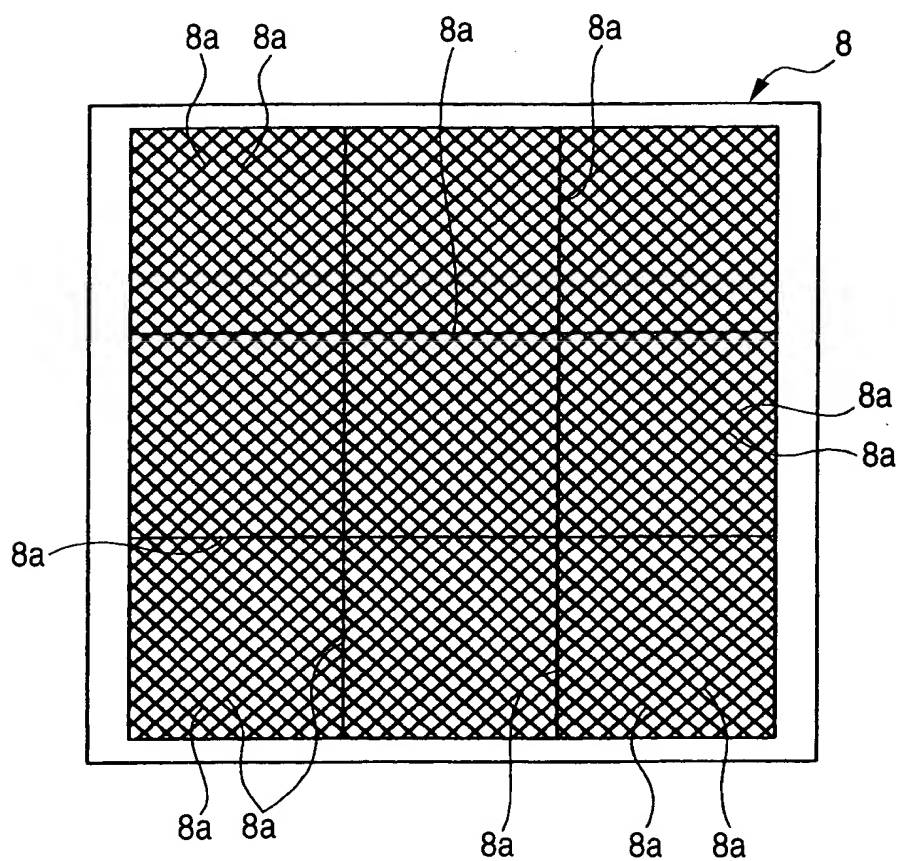


FIG. 12



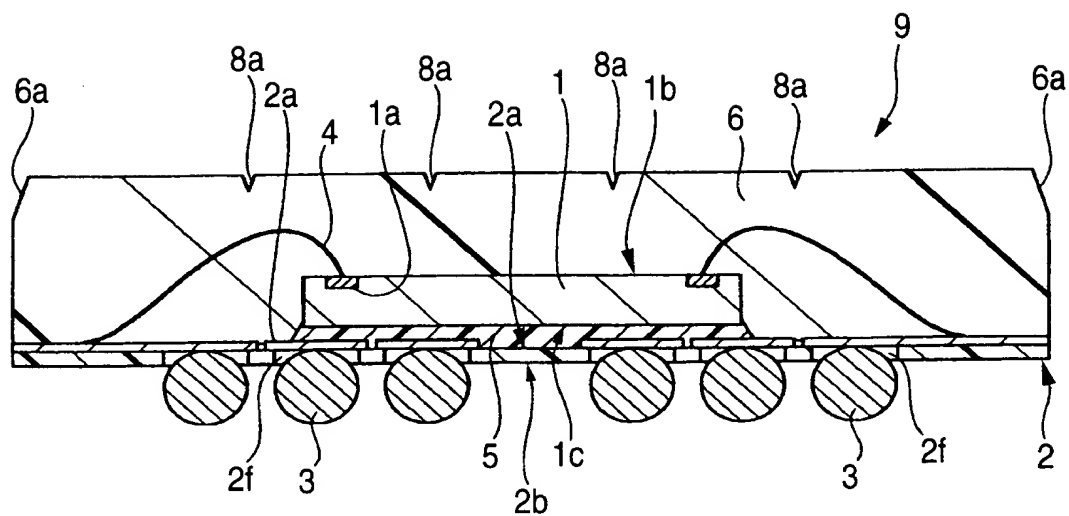
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FIG. 13



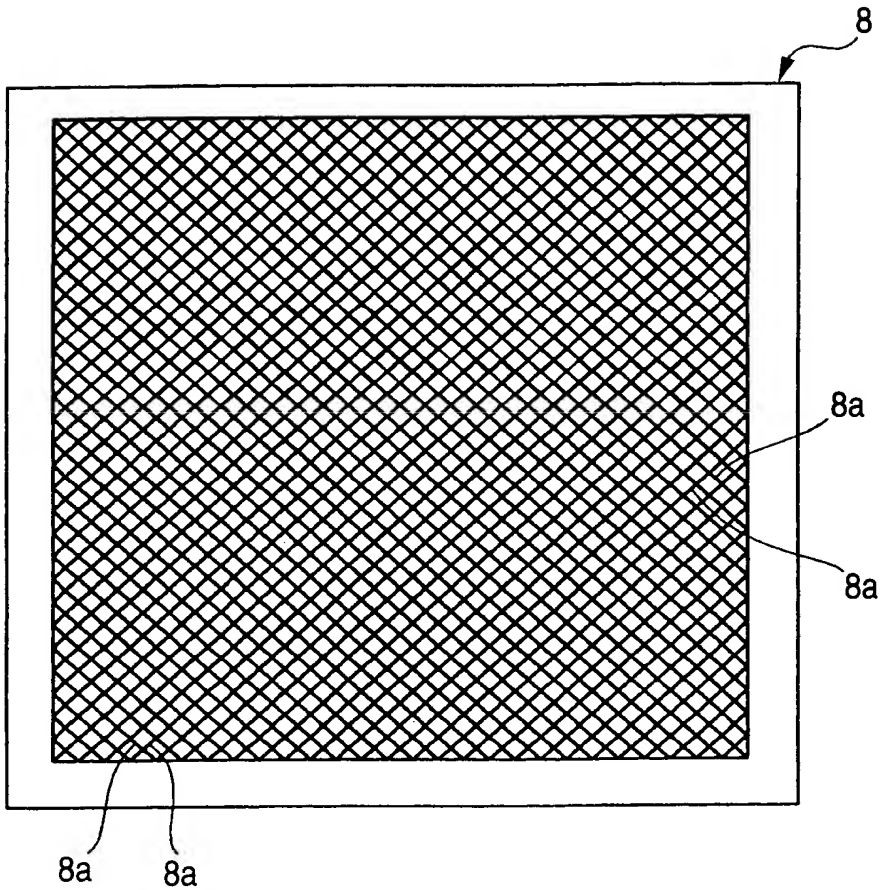
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FIG. 14



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FIG. 15



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FIG. 17A

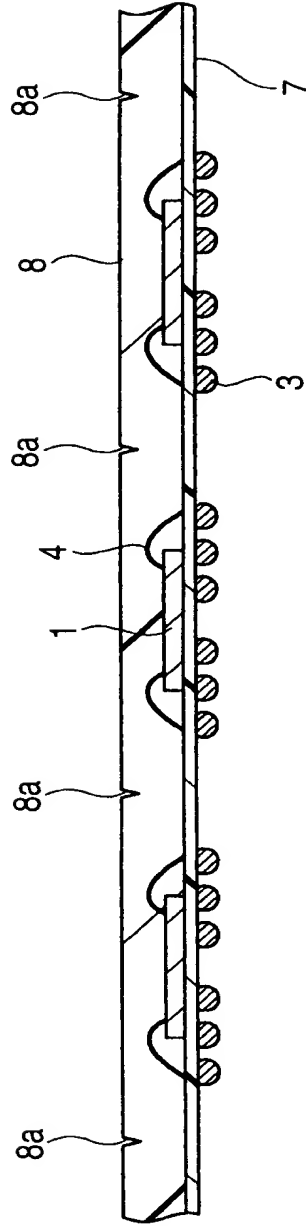


FIG. 17B

